

TinyLogic UHS Dual Buffer with 3-STATE Outputs NC7WZ241

Description

The NC7WZ241 is a Dual Non-Inverting Buffer with 3-STATE outputs. The output enable circuitry is organized as active LOW for one buffer and active HIGH for the other buffer, thus facilitating transceiver operation.

The Ultra High Speed device is fabricated with advanced CMOS technology to achieve superior switching performance with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} operating range. The inputs and outputs are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 5.5 V independent of V_{CC} operating range. Outputs tolerate voltages above V_{CC} when in the 3–STATE condition.

Features

- Space Saving US8 Surface Mount Package
- MicroPakTM Pb-Free Leadless Package
- Ultra High Speed: t_{PD} 2.6 ns Typ. into 50 pF at 5 V V_{CC}
- High Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- ullet Matches the Performance of LCX when Operated at 3.3 V V_{CC}
- Power Down High Impedance Inputs / Outputs
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Outputs are Overvoltage Tolerant in 3-STATE Mode
- Patented Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

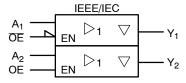


Figure 1. Logic Symbol

MARKING DIAGRAMS



UQFN8 1.6X1.6, 0.5P CASE 523AY





US8 CASE 846AN



T7, WZ41 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code

XY = 2-Digit Date Code Format

Z = Assembly Plant Code

A = Assembly Site

L = Wafer Lot Number

YW = Assembly Start Week

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

Connection Diagrams

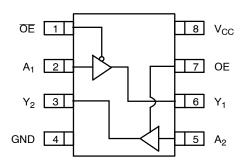


Figure 2. Pin Assignments for US8 (Top View)

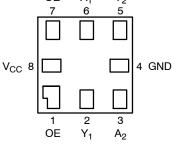
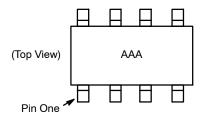


Figure 4. Pad Assignments for MicroPak (Top Thru View)



AAA represents Product Code Top Mark - see ordering code

NOTE: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

Figure 3. Pin One Orientation Diagram

PIN DESCRIPTIONS

Pin Names	Description
ŌĒ, OE	Enable Inputs for 3-STATE Outputs
A _n	Inputs
Y _n	3-STATE Outputs

FUNCTION TABLE

Inp	uts	Out	put
OE or OE	A _n	Y ₁	Y ₂
L	L	L	Z
L	Н	Н	Z
Н	L	Z	L
Н	Н	Z	Н

H = HIGH Logic Level L = LOW Logic Level

Z = 3-STATE

ABSOLUTE MAXIMUM RATINGS

Symbol	Parame	ter	Min	Max	Unit
V _{CC}	Supply Voltage		-0.5	6.5	V
V _{IN}	DC Input Voltage (Note 1)		-0.5	6.5	V
V _{OUT}	DC Output Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	-	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < 0 V	-	-50	mA
I _{OUT}	DC Output Source / Sink Current	DC Output Source / Sink Current			mA
I _{CC} / I _{GND}	DC V _{CC} / GND Current		-	±100	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature under Bias	-	+150	°C	
TL	Junction Lead Temperature (Solde	-	+260	°C	
P _D	Power Dissipation in Still Air	US8 MicroPak-8	- -	500 539	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol		Parameter	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Rete	ntion	1.5	5.5	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage	Active State	0	V _{CC}	V
		3-State	0	5.5	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 1.8 V, 0.15 V, 2.5 V ±0.2 V	0	20	ns/V
		V _{CC} = 3.3 V ±0.3 V	0	10	1
		V _{CC} = 5.0 V ±0.5 V	0	5	1
$\theta_{\sf JA}$	Thermal Resistance	US8 MicroPak-8	- -	250 232	°C/W

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

2. Unused inputs must be held HIGH or LOW. They may not float.

^{1.} The input and output negative voltage ratings may be exceeded is the input and output diode current ratings are observed.

DC ELECTICAL CHARACTERISTICS

					T _A = +25°C		T _A = -40	to +85°C		
Symbol	Parameter	Cond	litions	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input			1.65 to 1.95	0.65 V _{CC}	-	-	0.65 V _{CC}	=	٧
	Voltage			2.3 to 5.5	0.7 V _{CC}	_	-	0.7 V _{CC}	-	
V _{IL}	LOW Level Input			1.65 to 1.95	-	-	0.35 V _{CC}	-	0.35 V _{CC}	V
	Voltage			2.3 to 5.5	-	-	0.3 V _{CC}	-	0.3 V _{CC}	
V _{OH}	HIGH Level Output	$V_{IN} = V_{IH}$ or	$I_{OH} = -100 \mu A$	1.65	1.55	1.65	-	1.55	=	V
	Voltage	V _{IL}		2.3	2.2	2.3	-	2.2	=	
				3.0	2.9	3.0	-	2.9	=	
				4.5	4.4	4.5	-	4.4	=	
		V _{IN} = V _{IH} or	$I_{OH} = -4 \text{ mA}$	1.65	1.29	1.52	-	1.29	=	
		V _{IL}	I _{OH} = -8 mA	2.3	1.9	2.15	-	1.9	=	
			I _{OH} = -16 mA	3.0	2.4	2.80	-	2.4	=	
			I _{OH} = -24 mA	3.0	2.3	2.68	-	2.3	=	
			I _{OH} = -32 mA	4.5	3.8	4.20	-	3.8	=	
V_{OL}	LOW Level Output	$V_{IN} = V_{IH}$ or	I _{OL} = 100 μA	1.65	-	0.0	0.10	-	0.10	V
	Voltage	V _{IL}		2.3	-	0.0	0.10	-	0.10	
				3.0	-	0.0	0.10	-	0.10	
				4.5	-	0.0	0.10	-	0.10	
		V _{IN} = V _{IH} or	I _{OL} = 4 mA	1.65	-	0.08	0.24	-	0.24	
		V _{IL}	I _{OL} = 8 mA	2.3	-	0.10	0.3	-	0.3	
			I _{OL} = 16 mA	3.0	-	0.15	0.4	-	0.4	
			I _{OL} = 24 mA	3.0	-	0.22	0.55	-	0.55	
			I _{OL} = 32 mA	4.5	-	0.22	0.55	-	0.55	
I _{IN}	Input Leakage Current	$V_{IN} = 5.5 \text{ V, G}$	ND	1.65 to 5.5	_	-	±0.1	-	±1	μΑ
I _{OZ}	3-STATE Output Leakage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $0 \le V_{OUT} \le 5.5 \text{ V}$		1.65 to 5.5	_	-	±0.5	-	±5	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} or V _{OUT} = 5.5 V		0.0	_	-	1	-	10	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V, GI	ND	1.65 to 5.5	-	-	1	-	10	μΑ

NOISE CHARACTERISTICS

				$T_A = +25^{\circ}C$		
Symbol	Parameter	Conditions	V _{CC} (V)	Тур	Max	Unit
V _{OLP} (Note 3)	Quiet Output Maximum Dynamic V _{OL}	C _L = 50 pF	5.0	-	1.0	V
V _{OLV} (Note 3)	Quiet Output Minimum Dynamic V _{OL}	C _L = 50 pF	5.0	-	1.0	V
V _{OHV} (Note 3)	Quiet Output Minimum Dynamic VOH	C _L = 50 pF	5.0	=	4.0	V
V _{IHD} (Note 3)	Minimum HIGH Level Dynamic Input Voltage	C _L = 50 pF	5.0	=	3.5	V
V _{ILD} (Note 3)	Maximum LOW Level Dynamic Input Voltage	C _L = 50 pF	5.0	=	1.5	V

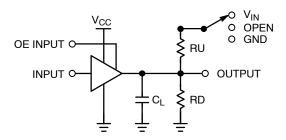
^{3.} Parameter guaranteed by design.

AC ELECTRICAL CHARACTERISTICS

				T _A = +25°C		T _A = -40	to +85°C				
Symbol	Parameter	Conditions	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit		
t _{PLH}	Propagation Delay	C _L = 15 pF	1.8 ±0.15	-	_	12.0	-	13.0	ns		
t _{PHL}	A _n to Y _n (Figure 5, 7)	$RD = 1 M\Omega$ $S_1 = OPEN$	2.5 ±0.2	-	-	7.5	-	8.0			
			3.3 ±0.3	_	_	5.2	-	5.5			
			5.0 ±0.5	_	-	4.5	-	4.8			
		C _L = 50 pF, RD = 500 Ω	3.3 ±0.3	_	-	5.7	-	6.0			
		$S_1 = OPEN$	5.0 ±0.5	-	_	5.0	-	5.3			
^t oslh	Output to Output Skew	C _L = 50 pF,	3.3 ±0.3	-	_	1.0	-	1.0	ns		
toshl	(Note 4) (Figure 5, 7)	RD = 500Ω S ₁ = Open	5.0 ±0.5	_	_	0.8	-	0.8			
t _{PZL}	Output Enable Time	C _L = 50 pF	1.8 ±0.15	-	_	14.0	-	15.0	ns		
t _{PZH}	(Figure 5, 7)	RD,RU = 500 Ω S ₁ = GND for t _{PZH}	2.5 ±0.2	_	_	8.5	-	9.0			
		$S_1 = V_I \text{ for } t_{PZL}$ $V_I = 2 \times V_{CC}$	$S_1 = V_1$ for t_{PZL} $V_1 = 2 \times V_{CC}$	3.3 ±0.3	-	-	6.2	-	6.5		
			5.0 ±0.5	_	-	5.5	-	5.8			
t _{PLZ}	Output Disable Time (Figure 5, 7)	$C_L = 50 \text{ pF}$ RD,RU = 500 Ω	1.8 ±0.15	_	-	12.0	-	13.0	ns		
t _{PHZ}	(Figure 5, 7)	$S_1 = GND$ for t_{PHZ}	2.5 ±0.2	_	-	8.0	-	8.5			
		$S_1 = V_I \text{ for } t_{PLZ}$ $V_I = 2 \times V_{CC}$	$S_1 = V_I \text{ for } t_{PLZ}$ $V_I = 2 \times V_{CC}$	$S_1 = V_I \text{ for } t_{PLZ}$ $V_I = 2 \times V_{CC}$	3.3 ±0.3	1	_	5.7	-	6.0	
			5.0 ±0.5	-	_	4.7	-	5.0			
C _{IN}	Input Capacitance		0	1	2.5	_	-	-	pF		
C _{OUT}	Output Capacitance		5.0	-	4	_	-	-	pF		
C _{PD}	Power Dissipation Capacitance (Note 5)	OE = GND OE = V _{CC}	3.3	-	10	-	-	_	pF		
	(Figure 6)	OL - VCC	5.0	-	12	-	-	-			

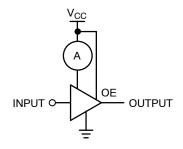
 ^{4.} Parameter guaranteed by design. t_{OSLH} = |t_{PLHmax} - t_{PLHmin}|; t_{OSHL} = |t_{PHLmax} - t_{PHLmin}|.
 5. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (see Figure 6) C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD} = (CPD) (V_{CC}) (f_{IN}) + (I_{CC}static).

AC Loading and Waveforms



 C_L includes load and stray capacitance Input PRR = 1.0 MHz; t_W = 500 ns

Figure 5. AC Test Circuit



Input = AC Waveform; $t_r = t_f = 1.8$ ns; PRR = 10 MHz; Duty Cycle = 50%.

Figure 6. I_{CCD} Test Circuit

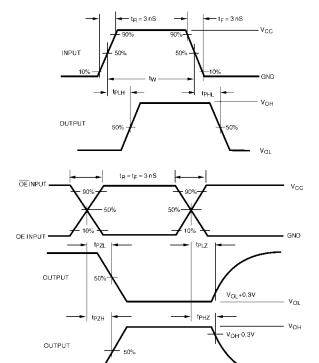


Figure 7. AC Waveforms

ORDERING INFORMATION

Order Number	Top Mark	Package	Shipping [†]
NC7WZ241K8X	WZ41	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ241K8X-L22236	WZ41	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ241L8X	Т7	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel
NC7WZ241L8X-L22185	Т7	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel

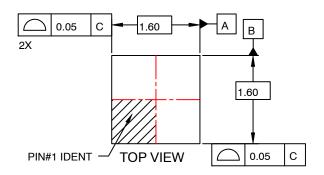
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

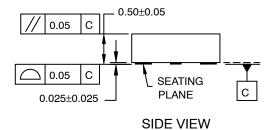
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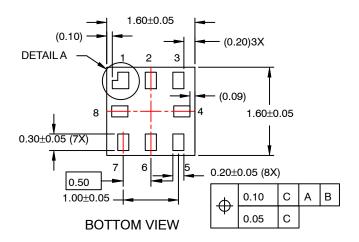
^{6.} Pb-Free package per JEDEC J-STD-020B.

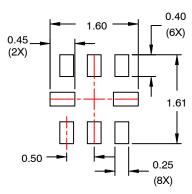
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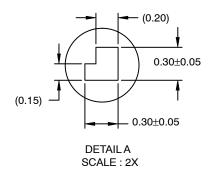




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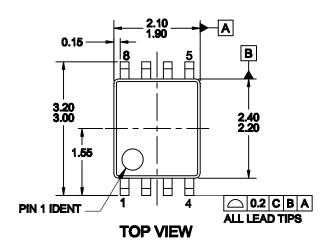


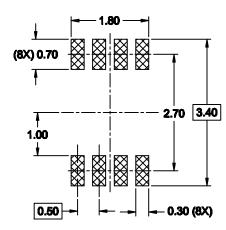
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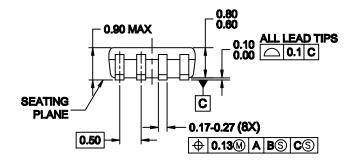
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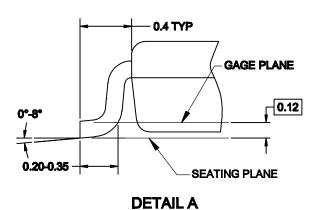
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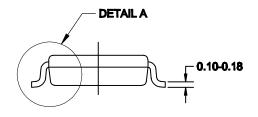


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SIDE VIEW





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